

LOW COST AREA ARRAY PROBE FOR CIRCUITS HAVING SOLDER-BALL CONTACTS ARE MANUFACTURED USING A WIRE BONDING MACHINE

Abstract

An inexpensive and accurate probe card for testing integrated circuits such as DSPs and the like which have solder ball contact points as manufactured by using a commercially available wire bonding machine. Conductive members or stud bumps are deposited or bonded to conductive pads formed on an insulating substrate. According to one embodiment, three stud bumps are formed on each pad to create an interconnecting nest to receive these solder ball contacts.

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